

ABSTRACT

The present invention relates to a method of producing a contactless chip card.

In a first step of the method, a card body with one or a plurality of recesses on one card body side is produced from a thermoplastic material, preferably by injection moulding. Subsequently, conductor tracks corresponding to a coil as a conductor track pattern are impressed directly onto surface areas of the card body side including the recesses using a hot impressing technique. The conductor tracks are impressed especially also onto surface areas inside the recesses. One or a plurality of chips are then aligned in the recesses and contacted with the conductor tracks in the recesses.

The method according to the present invention is advantageous insofar as it permits a simple production of a chip card, which requires only a few method steps and is therefore also economical. Furthermore, such a chip card is both mechanically stable and reliable, since it comprises very few individual layers and since the conductor tracks of the coil are applied directly to the card body.